

cup further comprising a processing fluid inlet that is in fluid communication with the processing fluid supply, processing fluid rising within the fluid cup overflowing the weir and flowing through the fluid flow region for recirculation to the processing fluid supply;

an electrode disposed within said fluid cup to facilitate electrochemical processing of a workpiece;

- a bowl-leveler connected between said process bowl and said frame for leveling said process bowl relative to said frame to facilitate uniform fluid flow across a surface of a workpiece under process.

41. The workpiece processing apparatus of claim 40 and further comprising a fluid cup height adjustment mechanism disposed to adjust the height of the fluid cup with respect to the process bowl.

42. (Amended) The workpiece processing apparatus of claim 40 wherein the bowl leveler comprises first, second and third adjustment mechanisms disposed peripherally about the process bowl.

43. The workpiece processing apparatus of claim 42 wherein the first, second and third adjustment mechanisms are individually adjustable.

44. The workpiece processing apparatus of claim 43 wherein the adjustment mechanisms comprise jack screws.

45. The workpiece processing apparatus of claim 42 wherein the adjustment mechanisms are positioned to facilitate left and right leveling and front and rear leveling.

46. The workpiece processing apparatus of claim 40 wherein the process bowl is connected to the fluid cup.

47. A reactor for sequentially processing single wafers pursuant to fabricating microelectronic components on the wafers, the reactor comprising:

a process head including a wafer support adapted to selectively engage and release a wafer;

a process base including a fluid cup having a weir over which processing fluid provided to the cup overflows, the process head being movable with respect to the process base to bring a wafer held by the wafer support into contact with the processing fluid in the fluid cup at a position proximate the weir;

a leveling mechanism disposed about the process base and positioned to allow the leveling of the fluid cup to assist in providing uniform fluid flow across a surface of the wafer under process.

48. (Amended) The reactor of claim 47 wherein the process base further comprises a process bowl, the fluid cup being disposed within the process bowl and defining a fluid flow region between an outer sidewall of the fluid cup and an inner sidewall of the process bowl, the fluid cup including an outer rim forming the weir.

49. The reactor of claim 48 and further comprising a fluid cup height adjustment mechanism disposed to adjust the height of the fluid cup with respect to the process bowl.

50. The reactor of claim 48 where in the leveling mechanism comprises first, second and third adjustment mechanisms disposed peripherally about the process bowl.

51. The reactor of claim 50 wherein the first, second and third adjustment mechanisms are individually adjustable.

52. The workpiece processing apparatus of claim 50 wherein the adjustment mechanisms comprise jack screws.

53. The workpiece processing apparatus of claim 50 wherein the adjustment mechanisms are positioned to facilitate left and right leveling and front and rear leveling.

54. An apparatus for sequentially processing single wafers pursuant to fabricating microelectronic components on the wafers, the reactor comprising:

- a wafer support;

- a process base including a fluid cup having a weir over which processing fluid provided to the cup overflows, a wafer held by the wafer support contacting the processing fluid in the fluid cup at a position proximate the weir;

- a leveling mechanism disposed about the process base and positioned to allow the leveling of the fluid cup to assist in providing uniform fluid flow across a surface of a wafer under process.

55. The reactor of claim 54 and further comprising a fluid cup height adjustment mechanism disposed to adjust the height of the fluid cup with respect to the process bowl.